

IA-3

Semiconductor Industry (Wafers and Disks) MARKET.

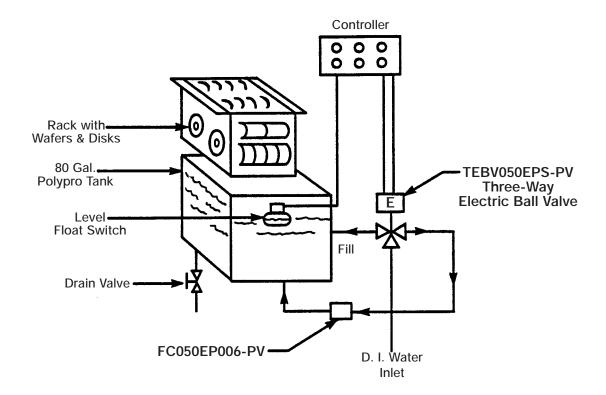
TEBV050EPS-PV, 3-Way Electric Actuated Ball Valve and PRODUCT(S)

FC050EP006-PV, Flow Control Valve.

REQUIREMENT_To provide constant flow of clean D. I. water across wafers and disks

D. I. Water PROCESS FLUID(S).

60 PSI / Ambient Temperature **INLET PRESSURE/TEMPERATURE**



Following the plating process of semiconductor wafers and disks they are loaded into a rinsing rack for final cleaning. The process starts by filling the rinse tank using the left port. Once the tank is filled the True Blue Electric Actuated Ball Valve switches porting to direct flow through the right

port, then through the 6 GPM Flow Control Valve. By maintaining a constant flow into the rinse tank, it now assures continuing cascade rinsing and cleaning. At the end of each eight (8) hour shift, the water is drained from the tanks and the process is repeated.